

特征/Features	外形尺寸/Outline Dimensions																																												
<ul style="list-style-type: none"> ◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V 	Case: KBU Series Dimensions in millimeters		<table border="1"> <thead> <tr> <th>序号</th> <th>Min(mm)</th> <th>MAX(mm)</th> </tr> </thead> <tbody> <tr><td>A</td><td>22.7</td><td>23.3</td></tr> <tr><td>B</td><td>18</td><td>18.6</td></tr> <tr><td>C</td><td>3.6</td><td>3.9</td></tr> <tr><td>D</td><td>5.7</td><td>5.9</td></tr> <tr><td>E</td><td>17.2</td><td>17.8</td></tr> <tr><td>F</td><td>18.7</td><td>19.3</td></tr> <tr><td>G</td><td>0.8</td><td>1.2</td></tr> <tr><td>H</td><td>4.9</td><td>5.4</td></tr> <tr><td>I</td><td>24.9</td><td>25.5</td></tr> <tr><td>J</td><td>1.3</td><td>1.7</td></tr> <tr><td>K</td><td>1.2</td><td>1.3</td></tr> <tr><td>L</td><td>4.6</td><td>4.9</td></tr> <tr><td>M</td><td>6.6</td><td>6.9</td></tr> </tbody> </table>	序号	Min(mm)	MAX(mm)	A	22.7	23.3	B	18	18.6	C	3.6	3.9	D	5.7	5.9	E	17.2	17.8	F	18.7	19.3	G	0.8	1.2	H	4.9	5.4	I	24.9	25.5	J	1.3	1.7	K	1.2	1.3	L	4.6	4.9	M	6.6	6.9
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机械参数/Machanical Data																																													
<ul style="list-style-type: none"> ◆ 本体：塑封 Case: plastic package ◆ 标识/极性：本体标记 Marking / Polarity: Marked on Body ◆ 重量：约克 Weight: About 6.66 rams 																																													

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

符号 Symbol	特性 Characteristic	KBU15							单位 Unit
		005	01	02	04	06	08	10	
V _{RRM}	最大反向重复峰值电压 Maxmum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
I _{F(AV)}	平均整流输出电流 Average Forward Output Rectified Current@Ta =120°C	15							A
V _F	正向峰值电压 Forward Voltage Per Leg @I _{FM} =15.0A	1.05							V
I _{FSM}	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	220							A
I _R	反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg	Ta = 25°C 5			Ta = 125°C 500				uA
i ² t	热容值 Rating for fusing (t<8.3ms)	200							A ² S
V _{isol}	绝缘耐压 Rms isolation voltage from case to leads	2500							V
C _J	典型结电容 Typical Junction Capacitance	50							pF
R _{θJC}	热阻 Maximum thermal resistance per leg	2							°C/W
T _J , T _{STG}	结温， 存储条件 Operating Junction and storage temperature range	-55~150							°C

Note:
 (1) Junction to case with heatsink
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

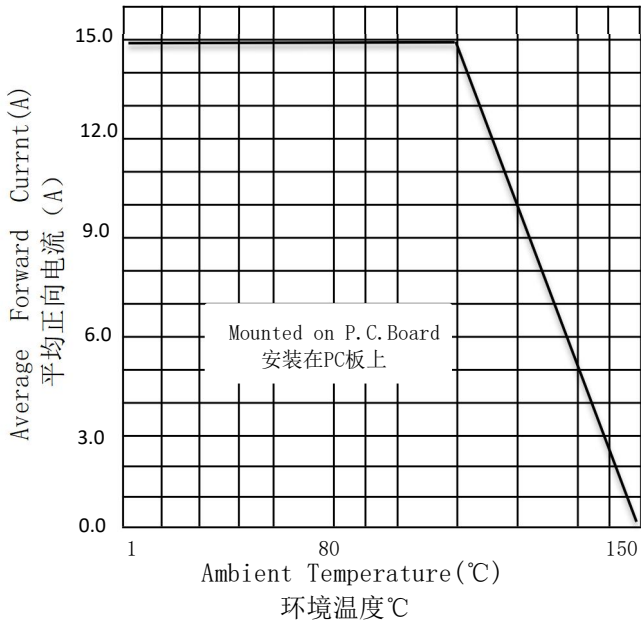


Fig.2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

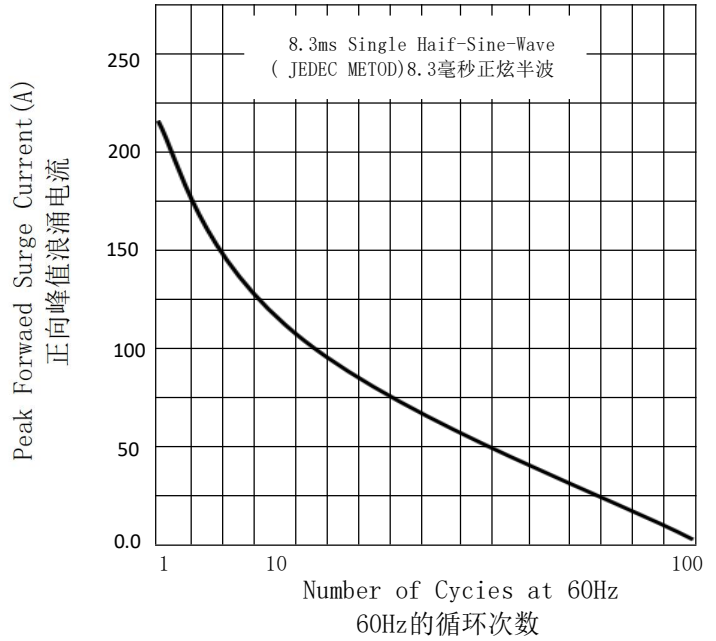


Fig.3-Typical Reverse Characteristics
图3. 典型的反向特性

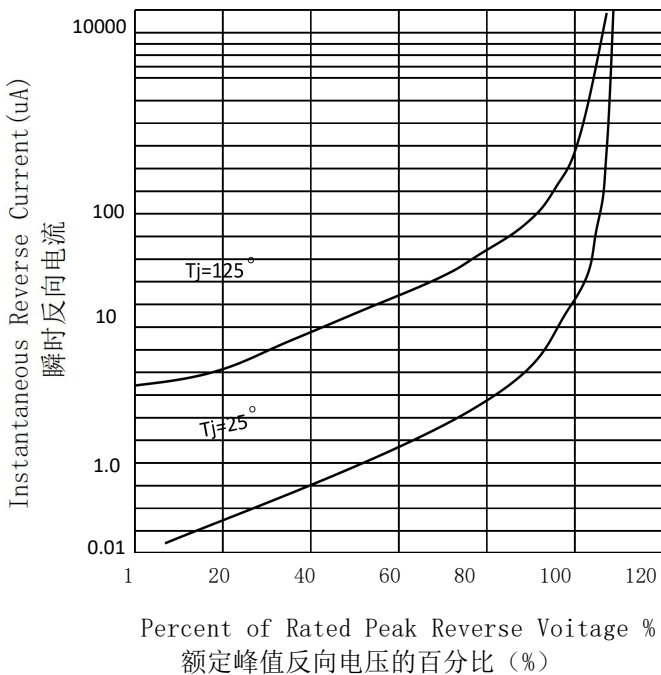


Fig.4-Typical Forward Characteristics
图4. 典型的正向特性

